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# FDC6331L Integrated Load Switch

### **General Description**

This device is particularly suited for compact power management in portable electronic equipment where 2.5V to 8V input and 2.8A output current capability are needed. This load switch integrates a small N-Channel power MOSFET (Q1) that drives a large PChannel power MOSFET (Q2) in one tiny SuperSOT<sup>TM</sup>-6 package.

# Applications

- Load switch
- Power management



Features

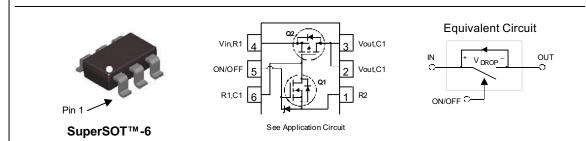
• Control MOSFET (Q1) includes Zener protection for ESD ruggedness (>6KV Human body model)

 $R_{DS(ON)}$  = 70 m $\Omega$  @ V<sub>GS</sub> = -2.5 V

 $R_{DS(ON)}$  = 100 m $\Omega$  @ V<sub>GS</sub> = -1.8 V

•  $-2.8 \text{ A}, -8 \text{ V}. \text{ R}_{\text{DS(ON)}} = 55 \text{ m}\Omega \text{ } \text{@ V}_{\text{GS}} = -4.5 \text{ V}$ 

+ High performance trench technology for extremely low  $R_{\text{DS}(\text{ON})}$ 



# Absolute Maximum Ratings T<sub>A</sub>=25°C unless otherwise noted

Symbol	Parameter		Ratings	Units	
V <sub>IN</sub>	Maximum II	nput Voltage		± 8	V
V <sub>ON/OFF</sub>	High level C	High level ON/OFF voltage range			V
Load	Load Curre	nt – Continuous	(Note 1)	2.8	A
	– Pulsed			9	
P₀	Maximum F	Power Dissipation	(Note 1)	0.7	W
Tj, Tstg	Operating and Storage Junction Temperature Range			–55 to +150	°C
	al Charac				
<b>Therma</b> R₀JA R₀JC	Thermal Re	teristics esistance, Junction-to-A esistance, Junction-to-C	. ,	180 60	°CM °CM
R <sub>θJA</sub> R <sub>θJC</sub>	Thermal Re Thermal Re	esistance, Junction-to-A	Case (Note 1)		
R₀ <sub>JA</sub> R₀ <sub>JC</sub> Packag	Thermal Re Thermal Re	esistance, Junction-to-A esistance, Junction-to-C	Case (Note 1)		

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Symbol	Parameter	Parameter Test Conditions		Тур	Max	Units
Off Cha	racteristics	·				
BVIN	Vin Breakdown Voltage	$V_{ON/OFF} = 0 V, I_D = -250 \mu A$	8			V
Load	Zero Gate Voltage Drain Current	V <sub>IN</sub> = 6.4 V, V <sub>ON/OFF</sub> = 0 V			_1	μA
I <sub>FL</sub>	Leakage Current, Forward	$V_{ON/OFF} = 0 V, V_{IN} = 8 V$			-100	nA
RL	Leakage Current, Reverse	$V_{ON/OFF} = 0 V, V_{IN} = -8 V$			100	nA
On Chai	acteristics (Note 2)					
V <sub>ON/OFF (th)</sub>	Gate Threshold Voltage	$V_{IN} = V_{ON/OFF}$ , $I_D = -250 \ \mu A$	0.4	0.9	1.5	V
R <sub>DS(on)</sub>	Static Drain–Source	$V_{GS} = -4.5 \text{ V}, \qquad I_D = -2.8 \text{A}$		34	55	mΩ
	On–Resistance (Q2)	$V_{GS} = -2.5 V$ , $I_D = -2.5 A$		45	70	
		$V_{GS} = -1.8 V$ , $I_D = -2.0 A$		64	100	
R <sub>DS(on)</sub>	Static Drain–Source	$V_{GS} = 4.5 \text{ V}, \qquad I_D = 0.4 \text{A}$		3.1	4	Ω
	On–Resistance (Q1)	$V_{GS} = 2.7 V$ , $I_D = 0.2 A$		3.8	5	

FDC6331L

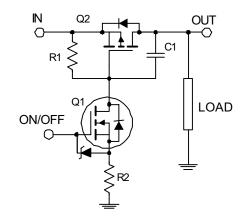
# **Drain–Source Diode Characteristics and Maximum Ratings**

s	Maximum Continuous Drain–Source Diode Forward Current			-0.6	A
V <sub>SD</sub>	Drain–Source Diode Forward Voltage	$V_{ON/OFF} = 0 V, I_S = -0.6 A$ (Note 2)		-1.2	V

Notes: 1. R <sub>8JA</sub> is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R  $_{\text{BJC}}$  is guaranteed by design while R  $_{\text{BJA}}$  is determined by the user's board design.

2. Pulse Test: Pulse Width < 300µs, Duty Cycle < 2.0%.

# FDC6331L Load Switch Application Circuit



External Component Recommendation: For additional in-rush current control, R2 and C1 can be added. For more information, see application note AN1030.

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0.4 0.4 V<sub>IN</sub> = 1.8V V<sub>IN</sub> = 2.5V V<sub>ON/OFF</sub> = 1.5V -8V PW = 300us, D < 2% 0.35 V<sub>ON/OFF</sub> = 1.5V -8V 0.35 PW = 300us, D < 2% 0.3 0.3  $= 125^{\circ}C$ T\_ = 125 °C 0.25 0.25 S S V<sub>DROP</sub> ( 0.2  $T_{J} = 25 \,{}^{O}C$ V<sub>DROP</sub> ( 0.2 25°C 0.15 0.15 0.1 0.1 0.05 0.05 0 0 0 1 2 3 4 5 6 0 1 2 3 4 5 6  $I_{L,}(A)$ I<sub>L,</sub> (A) Figure 1. Conduction Voltage Drop Figure 2. Conduction Voltage Drop Variation with Load Current. Variation with Load Current. 0.15 0.4 V<sub>IN</sub> = 4.5V V<sub>ON/OFF</sub> = 1.5V -8V PW = 300us, D < 2% I<sub>L</sub> = 1A Q2 0.35 V<sub>ON/OFF</sub> = 1.5V -8V ලි <sup>0.125</sup> PW = 300us, D < 2% 0.3 ON-RESISTANCE 0.1 0.25 S T\_= 125 °C دی ۵.2 ک ۵.15 ک 0.075 T \_ = 125<sup>0</sup>C 0.05  $T_J = 25^{\circ}C$ 0.1  $T_{\downarrow} = 25^{\circ}C$ <sub>0.025</sub> م 0.05 0 0 0 2 3 4 5 6 1 1  $^2$  -V<sub>gs</sub>, gate to source voltage (V) 5 I<sub>L,</sub> (A) Figure 3. Conduction Voltage Drop Figure 4. On-Resistance Variation Variation with Load Current. With Input Voltage 1 ŦŦĦĦ ╪╪╄ r(t), NORMALIZED EFFECTIVE TRANSIENT THERMAL RESISTANCE  $R_{\theta JA}(t) = r(t) + R_{\theta JA}$ R<sub>0</sub>JA = 156 °C/W . . . 111 P(pk) 0.1 ŧ t1 T」 - T<sub>A</sub> P \* R<sub>0JA</sub>(t) ┼┼┼ Duty Cycle, D = t1/ t2 111 0.01 0.0001 0.001 0.01 0.1 1 10 100 1000 Figure 5. Transient Thermal Response Curve. Thermal characterization performed on the conditions described in Note 2. Transient thermal response will change depends on the circuit board design.

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